

	L #	Hits	Search Text	DBs
1	L1	1	"07176310"	JPO
2	L2	2927	imp or (ion\$4 adj metal adj plasma)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
3	L3	2731	2 not (sputter\$3 or pvd or (physical adj2 deposition))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
4	L4	196	2 not 3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
5	L5	28	4 and wetting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
6	L6	2	5 and (splash\$3 or resputter\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
7	L7	194	4 not 8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
8	L8	134	7 not applied.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
9	L9	95	8 and (ti or titanium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
10	L10	8	9 and wetting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
11	L11	61	9 and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
12	L12	53	11 not 10	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
13	L13	385	204/298.07.ccis.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
14	L14	16	13 and (backside)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
15	L15	14	4 and (backside)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
16	L16	45	4 and ((gas or argon) near4 (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
17	L17	38	16 not (14 or 15)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB